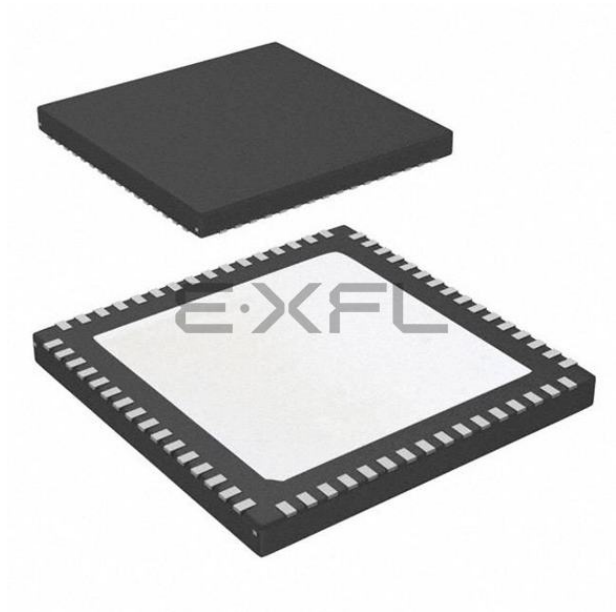
Renesas Electronics America Inc - R5F52315ADND#U0 Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	CANbus, I²C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	43
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-WFQFN Exposed Pad
Supplier Device Package	64-HWQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52315adnd-u0

1. Overview

1.1 Outline of Specifications

Table 1.1 lists the specifications, and Table 1.2 gives a comparison of the functions of the products in different packages.
Table 1.1 is for products with the greatest number of functions, so the number of peripheral modules and channels will differ in accordance with the package type. For details, see Table 1.2, Comparison of Functions for Different Packages.

Table 1.1 Outline of Specifications (1/4)

Classification	Module/Function	Description
CPU	CPU	• Maximum operating frequency: 54 MHz • 32-bit RX CPU (RX v2) • Minimum instruction execution time: One instruction per clock cycle • Address space: 4-Gbyte linear • Register set General purpose: Sixteen 32-bit registers Control: Ten 32-bit registers Accumulator: Two 72-bit registers • Basic instructions: 75 (variable-length instruction format) • Floating-point instructions: 11 • DSP instructions: 23 • Addressing modes: 10 • Data arrangement Instructions: Little endian Data: Selectable as little endian or big endian • On-chip 32-bit multiplier: 32-bit × 32-bit → 64-bit • On-chip divider: 32-bit ÷ 32-bit → 32 bits • Barrel shifter: 32 bits • Memory protection unit (MPU)
	FPU	• Single precision (32-bit) floating point • Data types and floating-point exceptions in conformance with the IEEE754 standard
Memory	ROM	• Capacity: 128/256/384/512 Kbytes • Up to 32 MHz: No-wait memory access 32 to 54 MHz: Wait state required. No wait state if the instruction is served by a ROM accelerator hit. • Programming/erasing method: Serial programming (asynchronous serial communication/USB communication), self-programming
	RAM	• Capacity: 32/64 Kbytes • 54 MHz, no-wait memory access
	E2 DataFlash	• Capacity: 8 Kbytes • Number of erase/write cycles: 1,000,000 (typ)
MCU operating mode		Single-chip mode, on-chip ROM enabled expansion mode, and on-chip ROM disabled expansion mode (software switching)
Clock	Clock generation circuit	• Main clock oscillator, sub-clock oscillator, low-speed on-chip oscillator, high-speed on-chip oscillator, PLL frequency synthesizer, USB-dedicated PLL frequency synthesizer, and IWDT-dedicated on-chip oscillator • Oscillation stop detection: Available • Clock frequency accuracy measurement circuit (CAC) • Independent settings for the system clock (ICLK), peripheral module clock (PCLK), external bus clock (BCLK), and FlashIF clock (FCLK) The CPU and system sections such as other bus masters run in synchronization with the system clock (ICLK): 54 MHz (at max.) MTU2a runs in synchronization with the PCLKA: 54 MHz (at max.) The ADCLK for the S12AD runs in synchronization with the PCLKD: 54 MHz (at max.) Peripheral modules other than MTU2a and S12ADE run in synchronization with the PCLKB: 32 MHz (at max.) Devices connected to external buses run in synchronization with the BCLK: 32 MHz (at max.) The flash peripheral circuit runs in synchronization with the FCLK: 32 MHz (at max.)
Resets		RES# pin reset, power-on reset, voltage monitoring reset, watchdog timer reset, independent watchdog timer reset, and software reset
Voltage detection	Voltage detection circuit (LVDAb)	• When the voltage on VCC falls below the voltage detection level, an internal reset or internal interrupt is generated. Voltage detection circuit 0 is capable of selecting the detection voltage from 4 levels Voltage detection circuit 1 is capable of selecting the detection voltage from 14 levels Voltage detection circuit 2 is capable of selecting the detection voltage from 4 levels

Table 1.5 Pin Functions (2/4)

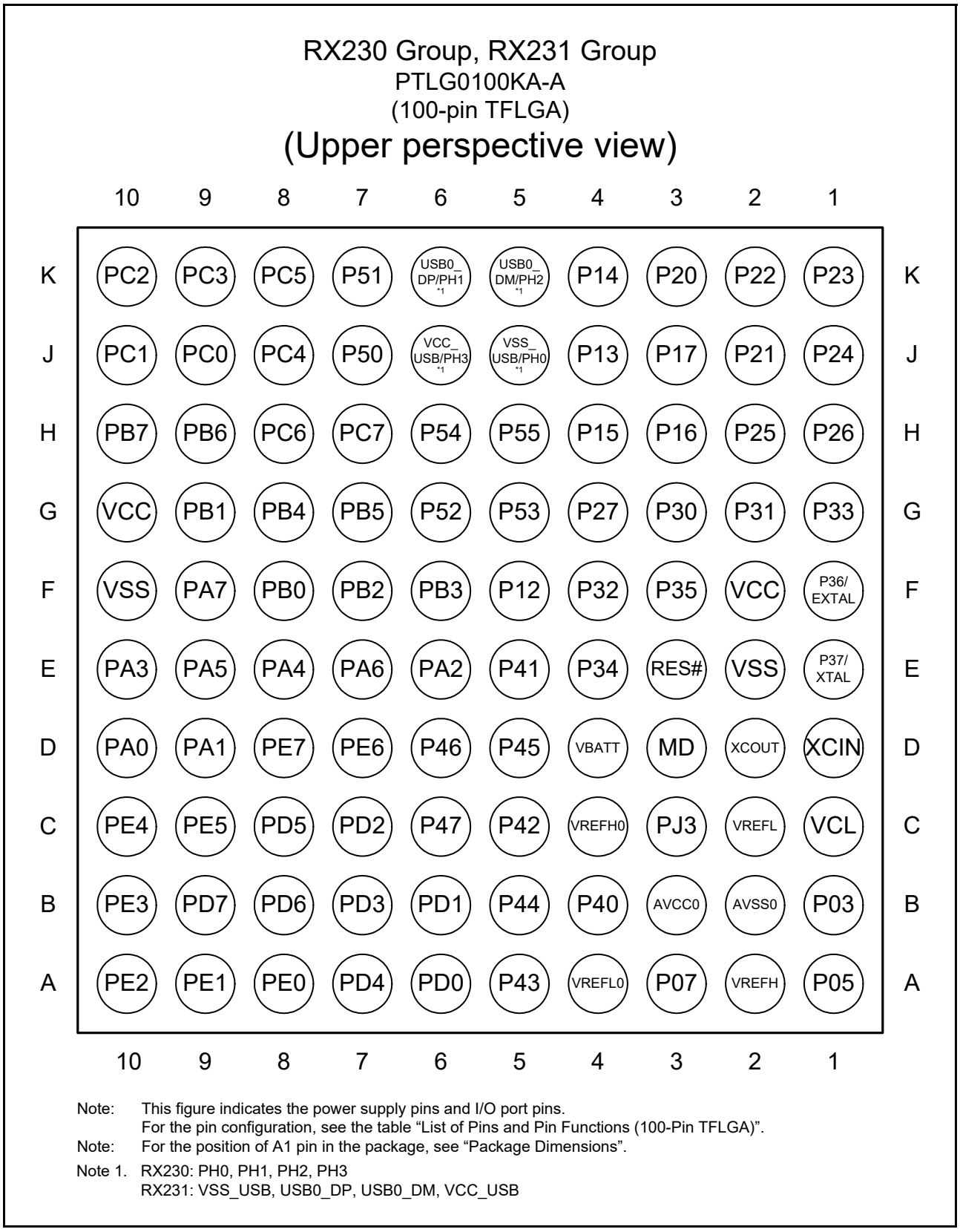
Classifications	Pin Name	I/O	Description
16-bit timer pulse unit	TIOCA0, TIOCB0 TIOCC0, TIOCD0	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	TIOCA1, TIOCB1	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	TIOCA2, TIOCB2	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	TIOCA3, TIOCB3 TIOCC3, TIOCD3	I/O	The TGRA3 to TGRD3 input capture input/output compare output/PWM output pins.
	TIOCA4, TIOCB4	I/O	The TGRA4 and TGRB4 input capture input/output compare output/PWM output pins.
	TIOCA5, TIOCB5	I/O	The TGRA5 and TGRB5 input capture input/output compare output/PWM output pins.
	TCLKA, TCLKB TCLKC, TCLKD	Input	Input pins for external clock signals.
Multi-function timer pulse unit 2	MTIOC0A, MTIOC0B MTIOC0C, MTIOC0D	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	MTIOC1A, MTIOC1B	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	MTIOC2A, MTIOC2B	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	MTIOC3A, MTIOC3B MTIOC3C, MTIOC3D	I/O	The TGRA3 to TGRD3 input capture input/output compare output/PWM output pins.
	MTIOC4A, MTIOC4B MTIOC4C, MTIOC4D	I/O	The TGRA4 to TGRD4 input capture input/output compare output/PWM output pins.
	MTIC5U, MTIC5V, MTIC5W	Input	The TGRU5, TGRV5, and TGRW5 input capture input/external pulse input pins.
	MTCLKA, MTCLKB, MTCLKC, MTCLKD	Input	Input pins for the external clock.
Port output enable 2	POE0# to POE3#, POE8#	Input	Input pins for request signals to place the MTU pins in the high impedance state.
Realtime clock	RTCOUT	Output	Output pin for the 1-Hz/64-Hz clock.
	RTCIC0 to RTCIC2	Input	Time capture event input pins.
8-bit timer	TMO0 to TMO3	Output	Compare match output pins.
	TMCI0 to TMCI3	Input	Input pins for the external clock to be input to the counter.
	TMRI0 to TMRI3	Input	Counter reset input pins.
Serial communications interface (SCIg)	• Asynchronous mode/clock synchronous mode		
	SCK0, SCK1, SCK5, SCK6, SCK8, SCK9	I/O	Input/output pins for the clock.
	RXD0, RXD1, RXD5, RXD6, RXD8, RXD9	Input	Input pins for received data.
	TXD0, TXD1, TXD5, TXD6, TXD8, TXD9	Output	Output pins for transmitted data.
	CTS0#, CTS1#, CTS5#, CTS6#, CTS8#, CTS9#	Input	Input pins for controlling the start of transmission and reception.
	RTS0#, RTS1#, RTS5#, RTS6#, RTS8#, RTS9#	Output	Output pins for controlling the start of transmission and reception.
	• Simple I^2C mode		
	SSCL0, SSCL1, SSCL5, SSCL6, SSCL8, SSCL9	I/O	Input/output pins for the I^2C clock.
	SSDA0, SSDA1, SSDA5, SSDA6, SSDA8, SSDA9	I/O	Input/output pins for the I^2C data.

Table 1.5 Pin Functions (3/4)

Classifications	Pin Name	I/O	Description
Serial communications interface (SCIg)	• Simple SPI mode		
	SCK0, SCK1, SCK5, SCK6, SCK8, SCK9	I/O	Input/output pins for the clock.
	SMISO0, SMISO1, SMISO5, SMISO6, SMISO8, SMISO9	I/O	Input/output pins for slave transmit data.
	SMOSI0, SMOSI1, SMOSI5, SMOSI6, SMOSI8, SMOSI9	I/O	Input/output pins for master transmit data.
	SS0#, SS1#, SS5#, SS6#, SS8#, SS9#	Input	Slave-select input pins.
IrDA interface	IRTXD5	Output	Data output pin in the IrDA format.
	IRRXD5	Input	Data input pin in the IrDA format.
Serial communications interface (SCIh)	• Asynchronous mode/clock synchronous mode		
	SCK12	I/O	Input/output pin for the clock.
	RXD12	Input	Input pin for receiving data.
	TXD12	Output	Output pin for transmitting data.
	CTS12#	Input	Input pin for controlling the start of transmission and reception.
	RTS12#	Output	Output pin for controlling the start of transmission and reception.
	• Simple I^2C mode		
	SSCL12	I/O	Input/output pin for the I^2C clock.
	SSDA12	I/O	Input/output pin for the I^2C data.
	• Simple SPI mode		
	SCK12	I/O	Input/output pin for the clock.
	SMISO12	I/O	Input/output pin for slave transmit data.
	SMOSI12	I/O	Input/output pin for master transmit data.
	SS12#	Input	Slave-select input pin.
	• Extended serial mode		
	RXDX12	Input	Input pin for data reception by SCIf.
	TXDX12	Output	Output pin for data transmission by SCIf.
	SIOX12	I/O	Input/output pin for data reception or transmission by SCIf.
I^2C bus interface	SCL	I/O	Input/output pin for I^2C bus interface clocks. Bus can be directly driven by the N-channel open drain output.
	SDA	I/O	Input/output pin for I^2C bus interface data. Bus can be directly driven by the N-channel open drain output.
Serial peripheral interface	RSPCKA	I/O	Input/output pin for the RSPI clock.
	MOSIA	I/O	Input/output pin for transmitting data from the RSPI master.
	MISOA	I/O	Input/output pin for transmitting data from the RSPI slave.
	SSLA0	I/O	Input/output pin to select the slave for the RSPI.
	SSLA1 to SSLA3	Output	Output pins to select the slave for the RSPI.
Serial sound interface	SSISCK0	I/O	SSI serial bit clock pin.
	SSIWS0	I/O	Word selection pin.
	SSITXD0	Output	Serial data output pin.
	SSIRXD0	Input	Serial data input pin.
	AUDIO_MCLK	Input	Master clock pin for audio.
CAN module	CRXD0	Input	Input pin
	CTXD0	Output	Output pin
SD host interface	SDHI_CLK	Output	SD clock output pin
	SDHI_CMD	I/O	SD command output, response input signal pin

1.5 Pin Assignments

Figure 1.3 to Figure 1.9 show the pin assignments. Table 1.6 to Table 1.10 show the lists of pins and pin functions.



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (100-Pin TFLGA)”.
Note: For the position of A1 pin in the package, see “Package Dimensions”.
Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.3 Pin Assignments of the 100-Pin TFLGA (Upper Perspective View)

Table 1.7 List of Pins and Pin Functions (100-Pin LFQFP) (1/3)

Pin No.	Power Supply, Clock, System Control	I/O Port	External Bus	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
1	VREFH							
2		P03						DA0
3	VREFL							
4		PJ3		MTIOC3C	CTS6#/RTS6#/SS6#			
5	VCL							
6	VBATT							
7	MD							FINED
8	XCIN							
9	XCOUT							
10	RES#							
11	XTAL	P37						
12	VSS							
13	EXTAL	P36						
14	VCC							
15	UPSEL	P35						NMI
16		P34		MTIOC0A/TMCI3/POE2#	SCK6		TS0	IRQ4
17		P33		MTIOC0D/TMRI3/POE3#/ TIOCD0	RXD6/SMISO6/SSCL6		TS1	IRQ3
18		P32		MTIOC0C/TMO3/TIOCC0/ RTCOUT/RTCIC2	TXD6/SMOSI6/SSDA6/ USB0_VBUSEN			IRQ2
19		P31		MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/ SSISCK0			IRQ1
20		P30		MTIOC4B/TMRI3/POE8#/ RTCIC0	RXD1/SMISO1/SSCL1/ AUDIO_MCLK			IRQ0/ CMPOB3
21		P27	CS3#	MTIOC2B/TMCI3	SCK1/ SSIWS0		TS2	CVREFB3
22		P26	CS2#	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1/ SSIRXD0		TS3	CMPB3
23		P25	CS1#	MTIOC4C/MTCLKB/ TIOCA4			TS4	ADTRG0#
24		P24	CS0#	MTIOC4A/MTCLKA/TMRI1/ TIOCB4	USB0_VBUSEN		TS5	
25		P23		MTIOC3D/MTCLKD/ TIOCD3	CTS0#/RTS0#/SS0#/ SSISCK0		TS6	
26		P22		MTIOC3B/MTCLKC/TMO0/ TIOCC3	SCK0/ USB0_OVRCURB/ AUDIO_MCLK		TS7	
27		P21		MTIOC1B/TMCI0/TIOCA3	RXD0/SMISO0/SSCL0/ USB0_EXICEN/SSIWS0		TS8	
28		P20		MTIOC1A/TMRI0/TIOCB3	TXD0/SMOSI0/SSDA0/ USB0_ID/SSIRXD0		TS9	
29		P17		MTIOC3A/MTIOC3B/TMO1/ POE8#/TIOCB0/TCLKD	SCK1/MISOA/SDA/ SSITXD0			IRQ7/ CMPOB2
30		P16		MTIOC3C/MTIOC3D/ TMO2/TIOCB1/TCLKC/ RTCOUT	TXD1/SMOSI1/SSDA1/ MOSIA/SCL/USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB			IRQ6/ ADTRG0#
31		P15		MTIOC0B/MTCLKB/TMCI2/ TIOCB2/TCLKB	RXD1/SMISO1/SSCL1/ CRXD0		TS12	IRQ5/CMPB2
32		P14		MTIOC3A/MTCLKA/TMRI2/ TIOCB5/TCLKA	CTS1#/RTS1#/SS1#/ CTXD0/USB0_OVRCURA		TS13	IRQ4/ CVREFB2
33		P13		MTIOC0B/TMO3/TIOCA5	SDA			IRQ3
34		P12		TMCI1	SCL			IRQ2
35	VCC_USB*1	PH3*1		TMCI0*1				
36		PH2*1		TMRI0*1	USB0_DM*1			IRQ1*1
37		PH1*1		TMO0*1	USB0_DP*1			IRQ0*1
38	VSS_USB*1	PH0*1						CACREF*1
39		P55	WAIT#	MTIOC4D/TMO3	CRXD0		TS15	
40		P54	ALE	MTIOC4B/TMCI1	CTXD0		TS16	
41	BCLK	P53					TS17	

Table 1.8 List of Pins and Pin Functions (64-Pin WFLGA) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
A1		P05					DA1
A2	AVCC0						
A3	VREFH0						
A4	VREFL0						
A5	VREFH						
A6	VREFL						
A7		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/ SSCL12			IRQ7/AN018/ CVREFB0
A8		PE3	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/ AUDIO_MCLK			AN019/CLKOUT
B1	VCL						
B2	AVSS0						
B3		P40					AN000
B4		P42					AN002
B5		P44					AN004
B6		P46					AN006
B7		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12			AN017/CMPB0
B8		PE4	MTIOC4D/MTIOC1A				AN020/CMPA2/ CLKOUT
C1	XCIN						
C2	MD						FINED
C3		P03					DA0
C4		P41					AN001
C5		P43					AN003
C6		PE0		SCK12			AN016
C7		PE5	MTIOC4C/MTIOC2B				IRQ5/AN021/ CMPOB0
C8		PA0	MTIOC4A/TIOCA0	SSLA1			CACREF
D1	XCOUT						
D2	RES#						
D3		P27	MTIOC2B/TMCI3	SCK1/ SSIWS0		TS2	CVREFB3
D4		P14	MTIOC3A/MTCLKA/TMRI2/ TIOCB5/TCLKA	CTS1#/RTS1#/SS1#/CTXD0/ USB0_OVRCURA		TS13	IRQ4/CVREFB2
D5		PA6	MTIC5V/MTCLKB/TMCI3/POE2#/ TIOCA2	CTS5#/RTS5#/SS5#/MOSIA/ SSIWS0			
D6		PA4	MTIC5U/MTCLKA/TMRI0/TIOCA1	TXD5/SMOSI5/SSDA5/SSLA0/ SSITXD0/IRTXD5			IRQ5 /CVREFB1
D7		PA1	MTIOC0B/MTCLKC/TIOCB0	SCK5/SSLA2/SSISCK0			
D8		PA3	MTIOC0D/MTCLKD/TIOCD0/ TCLKB	RXD5/SMISO5/SSCL5/SSIRXD0/ IRRXD5			IRQ6 /CMPB1
E1	VSS						
E2	VBATT						
E3		P30	MTIOC4B/TMRI3/POE8#/RTCIC0	RXD1/SMISO1/SSCL1/ AUDIO_MCLK			IRQ0/CMPOB3
E4		P16	MTIOC3C/MTIOC3D/TMO2/ TIOCB1/TCLKC/RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/ SCL/USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB			IRQ6/ADTRG0#
E5		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/SS8#/ SSLA0	SDHI_D1	TSCAP	
E6	VCC						
E7	VSS						
E8		PB0	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/RSPCKA	SDHI_C MD		
F1	VCC						
F2	UPSEL	P35					NMI
F3		P31	MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/SSISCK0			IRQ1

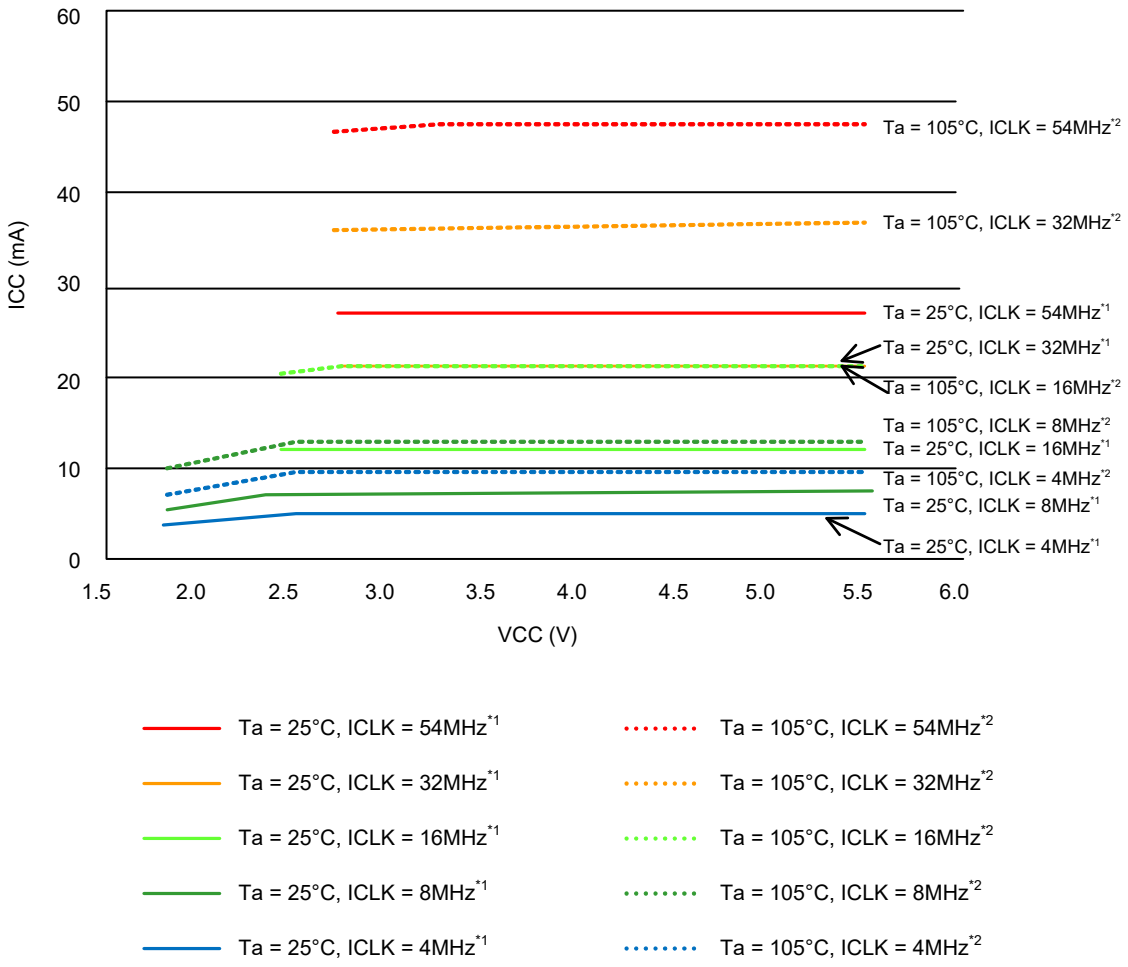
4.1 I/O Register Addresses (Address Order)

Table 4.1 List of I/O Registers (Address Order) (1/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 0000h	SYSTEM	Mode Monitor Register	MDMONR	16	16	3 ICLK	
0008 0006h	SYSTEM	System Control Register 0	SYSCR0	16	16	3 ICLK	
0008 0008h	SYSTEM	System Control Register 1	SYSCR1	16	16	3 ICLK	
0008 000Ch	SYSTEM	Standby Control Register	SBYCR	16	16	3 ICLK	
0008 0010h	SYSTEM	Module Stop Control Register A	MSTPCRA	32	32	3 ICLK	
0008 0014h	SYSTEM	Module Stop Control Register B	MSTPCRB	32	32	3 ICLK	
0008 0018h	SYSTEM	Module Stop Control Register C	MSTPCRC	32	32	3 ICLK	
0008 001Ch	SYSTEM	Module Stop Control Register D	MSTPCRD	32	32	3 ICLK	
0008 0020h	SYSTEM	System Clock Control Register	SCKCR	32	32	3 ICLK	
0008 0026h	SYSTEM	System Clock Control Register 3	SCKCR3	16	16	3 ICLK	
0008 0028h	SYSTEM	PLL Control Register	PLLCR	16	16	3 ICLK	
0008 002Ah	SYSTEM	PLL Control Register 2	PLLCR2	8	8	3 ICLK	
0008 002Ch	SYSTEM	USB-dedicated PLL Control Register	UPLLCR	16	16	3 ICLK	
0008 002Eh	SYSTEM	USB-dedicated PLL Control Register 2	UPLLCR2	8	8	3 ICLK	
0008 0030h	SYSTEM	External Bus Clock Control Register	BCKCR	8	8	3 ICLK	
0008 0031h	SYSTEM	Memory Wait Cycle Setting Register	MEMWAIT	8	8	3 ICLK	
0008 0032h	SYSTEM	Main Clock Oscillator Control Register	MOSCCR	8	8	3 ICLK	
0008 0033h	SYSTEM	Sub-Clock Oscillator Control Register	SOSCCR	8	8	3 ICLK	
0008 0034h	SYSTEM	Low-Speed On-Chip Oscillator Control Register	LOCOCR	8	8	3 ICLK	
0008 0035h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Control Register	ILOCOCR	8	8	3 ICLK	
0008 0036h	SYSTEM	High-Speed On-Chip Oscillator Control Register	HOCOCR	8	8	3 ICLK	
0008 0037h	SYSTEM	High-Speed On-Chip Oscillator Control Register 2	HOCOCR2	8	8	3 ICLK	
0008 003Ch	SYSTEM	Oscillation Stabilization Flag Register	OSCOVFSR	8	8	3 ICLK	
0008 003Eh	SYSTEM	CLKOUT Output Control Register	CKOCR	16	16	3 ICLK	
0008 0040h	SYSTEM	Oscillation Stop Detection Control Register	OSTDCR	8	8	3 ICLK	
0008 0041h	SYSTEM	Oscillation Stop Detection Status Register	OSTDSR	8	8	3 ICLK	
0008 0060h	SYSTEM	Low-Speed On-Chip Oscillator Trimming Register	LOCOTRR	8	8	3 ICLK	
0008 0064h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Trimming Register	ILOCOTRR	8	8	3 ICLK	
0008 0068h	SYSTEM	High-Speed On-Chip Oscillator Trimming Register 0	HOCOTRR0	8	8	3 ICLK	
0008 006Bh	SYSTEM	High-Speed On-Chip Oscillator Trimming Register 3	HOCOTRR3	8	8	3 ICLK	
0008 00A0h	SYSTEM	Operating Power Control Register	OPCCR	8	8	3 ICLK	
0008 00A1h	SYSTEM	Sleep Mode Return Clock Source Switching Register	RSTCKCR	8	8	3 ICLK	
0008 00A2h	SYSTEM	Main Clock Oscillator Wait Control Register	MOSCWTCR	8	8	3 ICLK	
0008 00AAh	SYSTEM	Sub Operating Power Control Register	SOPCCR	8	8	3 ICLK	
0008 00B0h	LPT	Low-Power Timer Control Register 1	LPTCR1	8	8	3 ICLK	
0008 00B1h	LPT	Low-Power Timer Control Register 2	LPTCR2	8	8	3 ICLK	
0008 00B2h	LPT	Low-Power Timer Control Register 3	LPTCR3	8	8	3 ICLK	
0008 00B4h	LPT	Low-Power Timer Cycle Setting Register	LPTPRD	16	16	3 ICLK	
0008 00B8h	LPT	Low-Power Timer Compare Register 0	LPCMR0	16	16	3 ICLK	
0008 00BCh	LPT	Low-Power Timer Standby Return Enable Register	LPWUCR	16	16	3 ICLK	
0008 00C0h	SYSTEM	Reset Status Register 2	RSTSR2	8	8	3 ICLK	
0008 00C2h	SYSTEM	Software Reset Register	SWRR	16	16	3 ICLK	
0008 00E0h	SYSTEM	Voltage Monitoring 1 Circuit Control Register 1	LVD1CR1	8	8	3 ICLK	
0008 00E1h	SYSTEM	Voltage Monitoring 1 Circuit Status Register	LVD1SR	8	8	3 ICLK	
0008 00E2h	SYSTEM	Voltage Monitoring 2 Circuit Control Register 1	LVD2CR1	8	8	3 ICLK	
0008 00E3h	SYSTEM	Voltage Monitoring 2 Circuit Status Register	LVD2SR	8	8	3 ICLK	
0008 03FEh	SYSTEM	Protect Register	PRCR	16	16	3 ICLK	
0008 1300h	BSC	Bus Error Status Clear Register	BERCLR	8	8	2 ICLK	
0008 1304h	BSC	Bus Error Monitoring Enable Register	BEREN	8	8	2 ICLK	

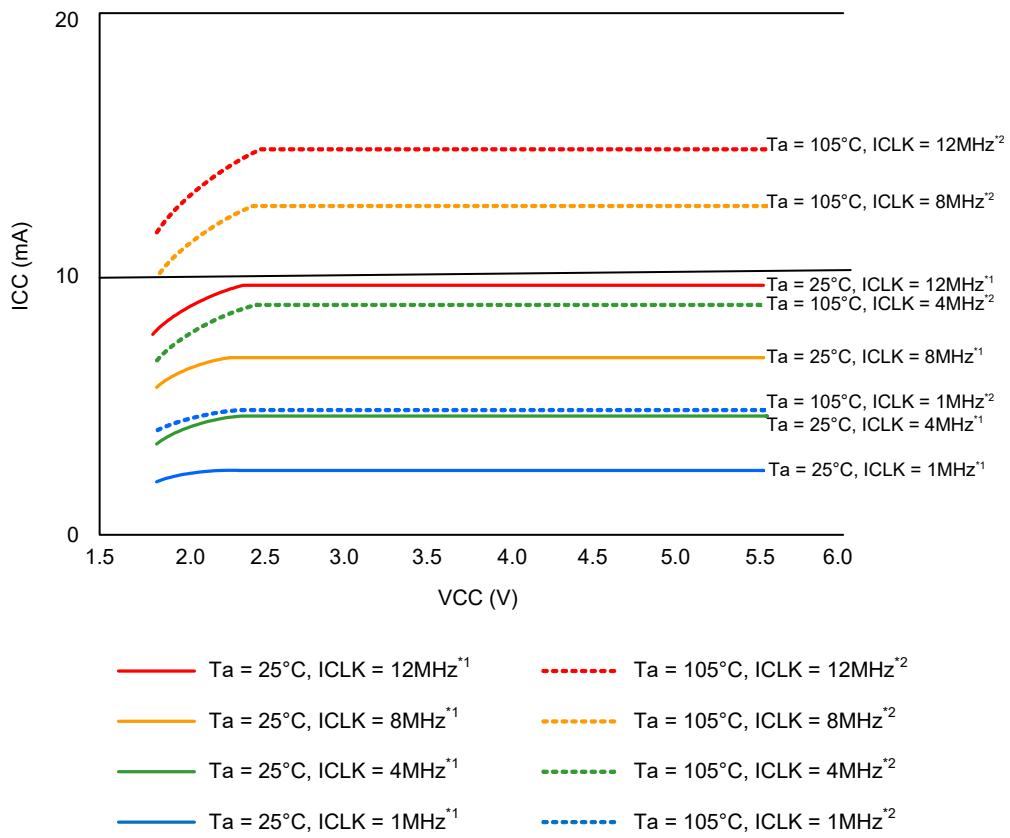
Table 4.1 List of I/O Registers (Address Order) (12/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 A131h	SCI9	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A132h	SCI9	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A500h	SSI0	Control Register	SSICR	32	32	2 or 3 PCLKB	2 ICLK
0008 A504h	SSI0	Status Register	SSISR	32	32	2 or 3 PCLKB	2 ICLK
0008 A510h	SSI0	FIFO Control Register	SSIFCR	32	32	2 or 3 PCLKB	2 ICLK
0008 A514h	SSI0	FIFO Status Register	SSIFSR	32	32	2 or 3 PCLKB	2 ICLK
0008 A518h	SSI0	Transmit FIFO Data Register	SSIFTDR	32	32	2 or 3 PCLKB	2 ICLK
0008 A51Ch	SSI0	Receive FIFO Data Register	SSIFRDR	32	32	2 or 3 PCLKB	2 ICLK
0008 A520h	SSI0	TDM Mode Register	SSITDMR	32	32	2 or 3 PCLKB	2 ICLK
0008 AC00h	SDHI	Command Register	SDCMD	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC08h	SDHI	Argument Register	SDARG	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC10h	SDHI	Data Stop Register	SDSTOP	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC14h	SDHI	Block Count Register	SDBLKCNT	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC18h	SDHI	Response Register 10	SDRSP10	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC20h	SDHI	Response Register 32	SDRSP32	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC28h	SDHI	Response Register 54	SDRSP54	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC30h	SDHI	Response Register 76	SDRSP76	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC38h	SDHI	SD Status Register 1	SDSTS1	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC3Ch	SDHI	SD Status Register 2	SDSTS2	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC40h	SDHI	SD Interrupt Mask Register 1	SDIMSK1	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing



Note 1. All peripheral operations except any BGO operation are operating normally. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. All peripheral operations except any BGO operation are operating at maximum. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

Figure 5.1 Voltage Dependency in High-Speed Operating Mode (Reference Data)



Note 1. All peripheral operations except any BGO operation are operating normally. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. All peripheral operations except any BGO operation are operating at maximum. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

Figure 5.2 Voltage Dependency in Middle-Speed Operating Mode (Reference Data)

Table 5.11 DC Characteristics (9)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.*7	Max.	Unit	Test Conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	—	0.7	1.7	mA	
	During A/D conversion (in low-current mode)		—	0.6	1.0		
	During D/A conversion (per channel)*1		—	0.4	0.8		
	Waiting for A/D and D/A conversion (all units)		—	—	0.4	μA	
Reference power supply current	During A/D conversion (at high-speed conversion)	I_{REFH0}	—	25	150	μA	
	Waiting for A/D conversion (all units)		—	—	60	nA	
	During D/A conversion (per channel)	I_{REFH}	—	50	100	μA	
	Waiting for D/A conversion (all units)		—	—	100	nA	
LVD1, 2	per channel	I_{LVD}	—	0.15	—	μA	
Temperature sensor*6	—	I_{TEMP}	—	75	—	μA	
Comparator B operating current*6	Window mode	I_{CMP}*5	—	12.5	28.6	μA	
	Comparator high-speed mode (per channel)		—	3.2	16.2	μA	
	Comparator low-speed mode (per channel)		—	1.7	4.4	μA	
CTSU operating current	When sleep mode Base clock frequency: 2MHz Pin capacitance: 50pF	I_{CTSU}	—	150	—	μA	
USB operating current*4	During USB communication operation under the following settings and conditions • Host controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect peripheral devices via a 1-meter USB cable from the USB port.	I_{USBH}*2	—	4.3 (VCC) 0.9 (VCC_USB)	—	mA	
	During USB communication operation under the following settings and conditions • Function controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect the host device via a 1-meter USB cable from the USB port.	I_{USBF}*2	—	3.6 (VCC) 1.1 (VCC_USB)	—	mA	
	During suspended state under the following setting and conditions • Function controller operation is set to full-speed mode (pull up the USB0_DP pin) • Software standby mode • Connect the host device via a 1-meter USB cable from the USB port.	I_{SUSP}*3	—	0.35 (VCC) 170 (VCC_USB)	—	μA	

Note 1. The value of the D/A converter is the value of the power supply current including the reference current.
Note 2. Current consumed only by the USB module.
Note 3. Includes the current supplied from the pull-up resistor of the USB0_DP pin to the pull-down resistor of the host device, in addition to the current consumed by this MCU during the suspended state.
Note 4. Current consumed by the power supplies (VCC and VCC_USB).
Note 5. Current consumed only by the comparator B module.
Note 6. Current consumed by the power supply (VCC).
Note 7. When VCC = AVCC0 = VCC_USB = 3.3 V.

Table 5.12 DC Characteristics (10)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

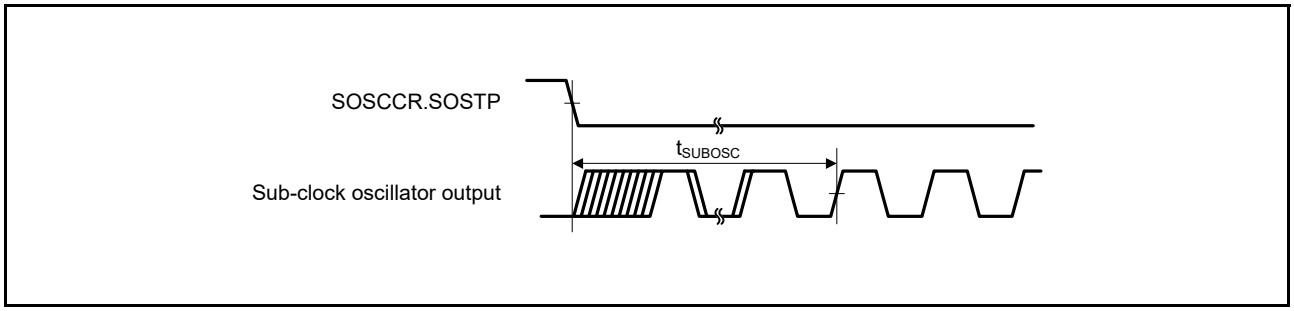


Figure 5.30 Sub-Clock Oscillation Start Timing

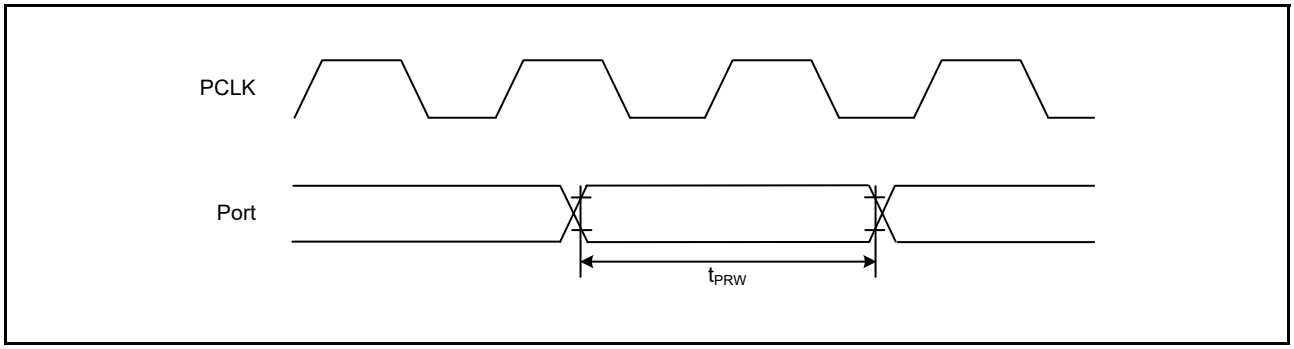


Figure 5.45 I/O Port Input Timing

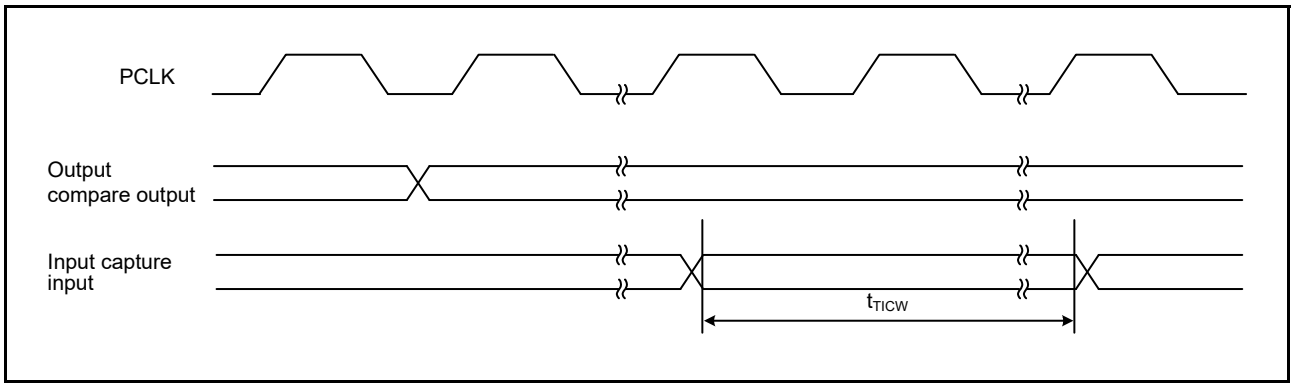


Figure 5.46 MTU2 Input/Output Timing

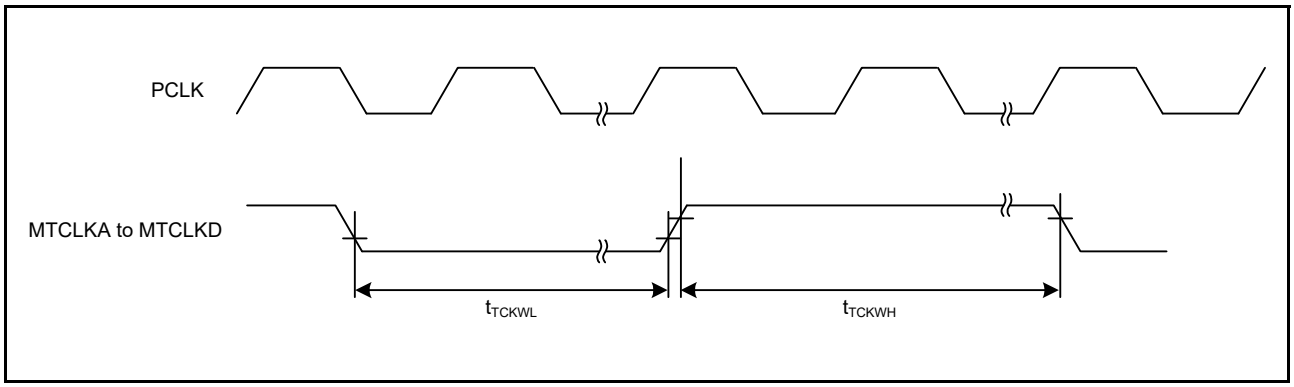


Figure 5.47 MTU2 Clock Input Timing

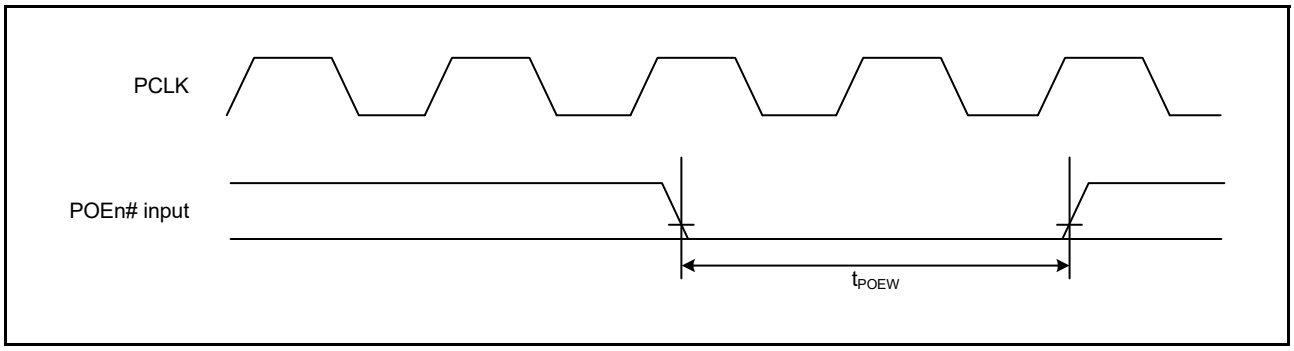


Figure 5.48 POE# Input Timing

Table 5.47 A/D Conversion Characteristics (2)

Conditions: 2.4 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, 2.4 V ≤ VREFH0 ≤ AVCC0, reference voltage = VREFH0 selected, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	32	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 32 MHz)	Permissible signal source impedance (Max.) = 1.3 kΩ	1.41	—	—	μs	High-precision channel The ADCSR.ADHSC bit is 0 The ADSSTRn register is 0Dh
		2.25	—	—		Normal-precision channel The ADCSR.ADHSC bit is 0 The ADSSTRn register is 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included Figure 5.68
Analog input resistance	Rs	—	—	2.5	kΩ	Figure 5.68
Offset error		—	±0.5	±4.5	LSB	
Full-scale error		—	±0.75	±4.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential non-linearity error		—	±1.0	—	LSB	
INL integral non-linearity error		—	±1.0	±4.5	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential non-linearity error, and INL integral non-linearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

5.6 D/A Conversion Characteristics

Table 5.52 D/A Conversion Characteristics (1)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C
Reference voltage = VREFH or VREFL selected

Item	Min.	Typ.	Max.	Unit	Test Conditions
Resolution	—	—	12	Bit	
Resistive load	30	—	—	kΩ	
Capacitive load	—	—	50	pF	
Output voltage range	0.35	—	AVCC0 - 0.47	V	
DNL differential non-linearity error	—	±0.5	±1.0	LSB	
INL integral non-linearity error	—	±2.0	±8.0	LSB	
Offset error	—	—	±20	mV	
Full-scale error	—	—	±20	mV	
Output resistance	—	5	—	Ω	
Conversion time	—	—	30	μs	

Table 5.53 D/A Conversion Characteristics (2)

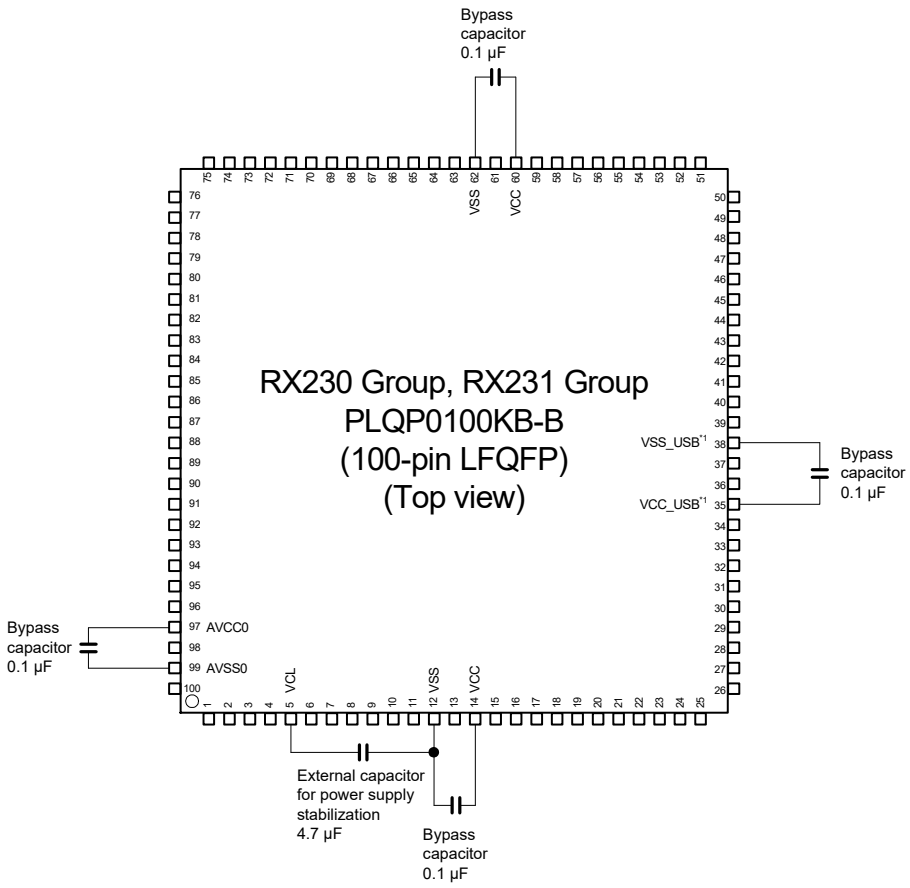
Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL = VSS_USB = 0 V, T_a = –40 to +105°C
Reference voltage = AVCC0 or AVSS0 selected

Item	Min.	Typ.	Max.	Unit	Test Conditions
Resolution	—	—	12	Bit	
Resistive load	30	—	—	kΩ	
Capacitive load	—	—	50	pF	
Output voltage range	0.35	—	AVCC0 - 0.47	V	
DNL differential non-linearity error	—	±0.5	±2.0	LSB	
INL integral non-linearity error	—	±2.0	±8.0	LSB	
Offset error	—	—	±30	mV	
Full-scale error	—	—	±30	mV	
Output resistance	—	5	—	Ω	
Conversion time	—	—	30	μs	

Table 5.54 D/A Conversion Characteristics (3)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C
Reference voltage = internal reference voltage selected

Item	Min.	Typ.	Max.	Unit	Test Conditions
Resolution	—	—	12	Bit	
Internal reference voltage (Vbgr)	1.36	1.43	1.50	V	
Resistive load	30	—	—	kΩ	
Capacitive load	—	—	50	pF	
Output voltage range	0.35	—	Vbgr	V	
DNL differential non-linearity error	—	±2.0	±16.0	LSB	
INL integral non-linearity error	—	±8.0	±16.0	LSB	
Offset error	—	—	30	mV	
Output resistance	—	5	—	Ω	
Conversion time	—	—	30	μs	



Note: Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic capacitor for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

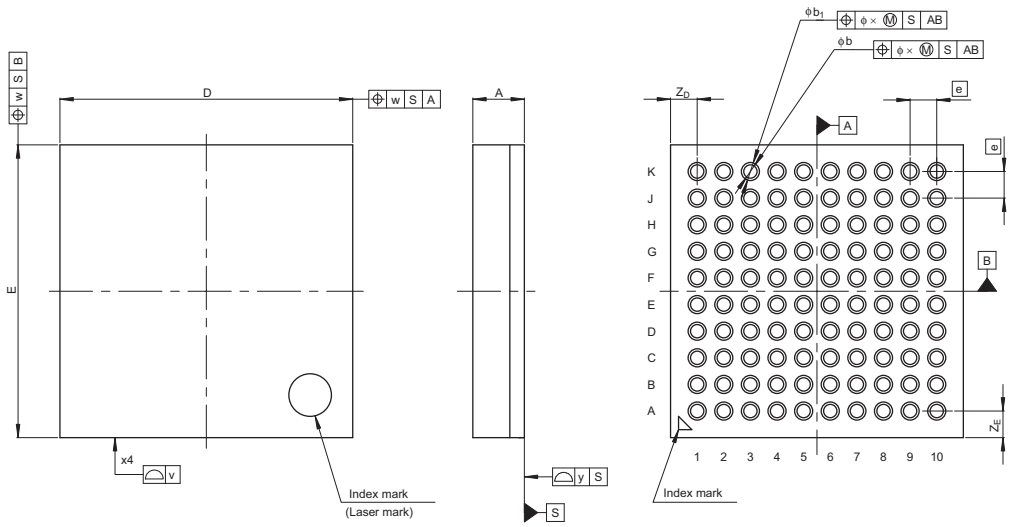
Note 1. As the products of the RX230 group do not have VCC_USB or VSS_USB, a bypass capacitor is not required.

Figure 5.80 Connecting Capacitors (100 Pins)

Appendix 1. Package Dimensions

Information on the latest version of the package dimensions or mountings has been displayed in “Packages” on Renesas Electronics Corporation website.

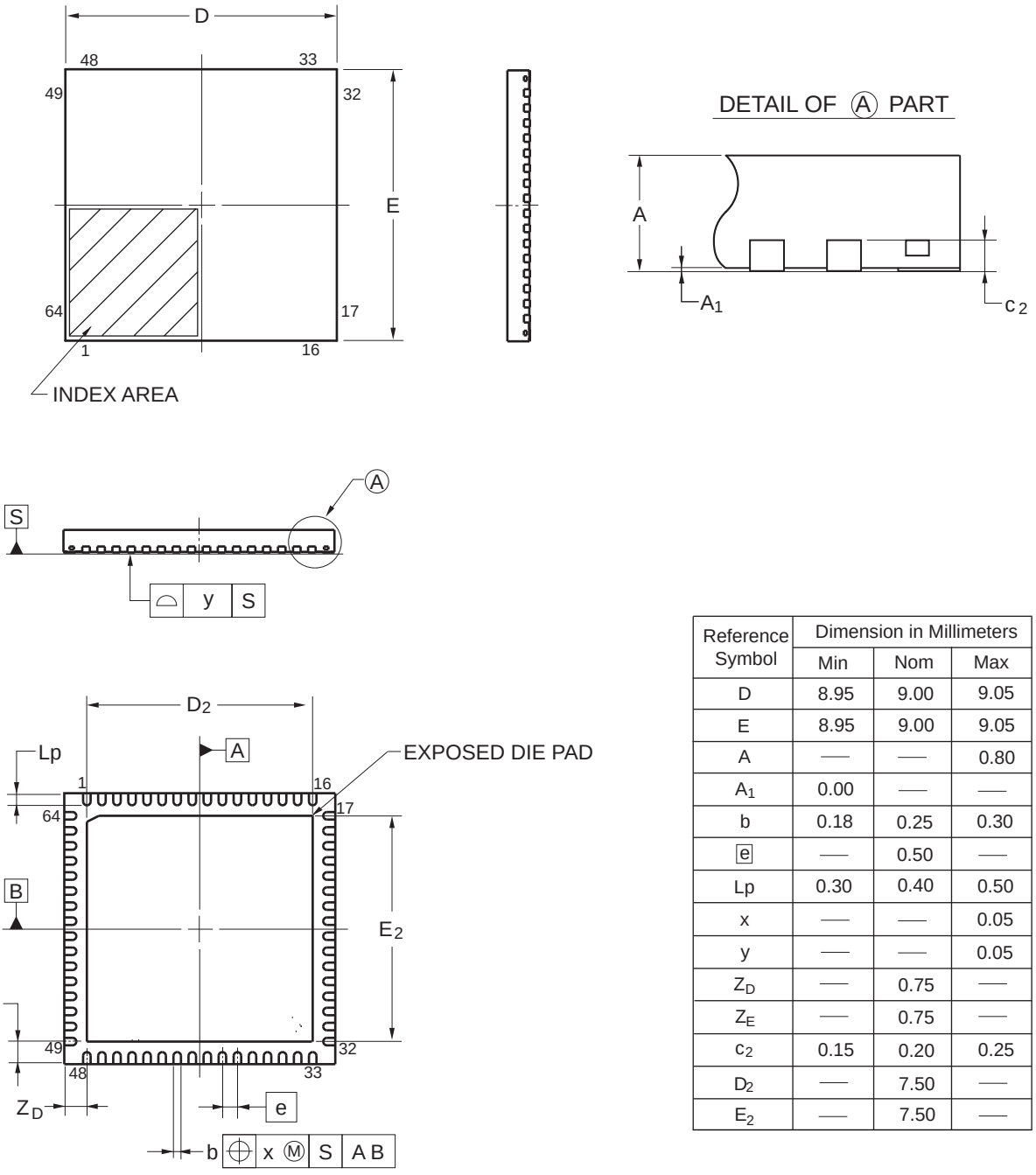
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA100-5.5x5.5-0.50	PTLG0100KA-A	100F0M	0.1g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	5.5	—
E	—	5.5	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.5	—
b	0.21	0.25	0.29
b_1	0.29	0.34	0.39
x	—	—	0.08
y	—	—	0.08
Z_D	—	0.5	—
Z_E	—	0.5	—

Figure A 100 -Pin TFLGA (PTLG0100KA-A)

JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN64-9x9-0.50	PWQN0064KC-A	P64K8-50-6B4-5	0.21



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	8.95	9.00	9.05
E	8.95	9.00	9.05
A	—	—	0.80
A_1	0.00	—	—
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05
Z_D	—	0.75	—
Z_E	—	0.75	—
c_2	0.15	0.20	0.25
D_2	—	7.50	—
E_2	—	7.50	—

Figure D 64 -Pin HWQFN (PWQN0064KC-A)

NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.